

Number of Components:	Two	Minimum Bond Line Cure Schedule*:	
Mix Ratio By Weight:	100:15	150°C	1 Hour
Specific Gravity:			
Part A	2.69		
Part B	1.22		
Pot Life:	8 Hours		
Shelf Life:	One year at room temperature		

*Note: Container(s) should be kept closed when not in use. For filled systems, mix contents of each container (A & B) thoroughly before mixing the two together. *Please see Applications Note available on our website.*

Product Description:

EPO-TEK[®] H77T is a two component, thermally conductive, electrically insulating epoxy designed for lid-sealing of hybrids found in hermetic packaging of micro-electronics. Lids can be ceramic, glass, aluminum or kovar. Package types can be plastic, metal cases or ceramic.

EPO-TEK[®] H77T Advantages & Application Notes:

- High temperature epoxy. Coatings on metals have been subjected to temperatures as high as 260°C without bond failure; can also resist >300°C processes found in ceramic or hermetic packaging.
- Rheology yields a thixotropic paste intended for dispensing and printing applications.
- Available in lower viscosity for better flow properties. Contact techserv@epotek.com for your best match.
- Excellent solvent and chemical resistance - ideal for harsh environments found in aircraft, under-hood automotive, medical, and petrochemical refineries such as down-hole applications.
- Can provide near hermetic seals in the packaging of MEMs devices, like pressure sensors or accelerometers, packaged in TO-cans.
- Suggested for ultra-high vacuum applications.
- It can also be used for sealing of optical filter windows found in scientific OEM or sensor devices.

Typical Properties: *(To be used as a guide only, not as a specification. Data below is not guaranteed. Different batches, conditions and applications yield differing results; Cure condition: 150°C/ 1 hour; * denotes test on lot acceptance basis)*

Physical Properties:	
*Color: Part A: Grey Part B: Amber	Die Shear Strength @ 23°C: ≥ 5 Kg /1,700 psi
*Consistency: Paste	Degradation Temp. (TGA): 413°C
*Viscosity (@ 10 RPM/23°C): 23,000 – 34,000 cPs	Weight Loss:
Thixotropic Index: 3.0	@ 200°C: < 0.05%
*Glass Transition Temp.(Tg): ≥ 80°C (Dynamic Cure	@ 250°C: 0.08%
20—200°C /ISO 25 Min; Ramp -10—200°C @ 20°C/Min)	@ 300°C: 0.22%
Coefficient of Thermal Expansion (CTE):	Operating Temp:
Below Tg: 34 x 10 ⁻⁶ in/in/°C	Continuous: - 55°C to 260°C
Above Tg: 127 x 10 ⁻⁶ in/in/°C	Intermittent: - 55°C to 360°C
Shore D Hardness: 89	Storage Modulus @ 23°C: 782,724 psi
Lap Shear Strength @ 23°C: 1,215 psi	*Particle Size: ≤ 50 Microns
Thermal Properties:	
Thermal Conductivity: 1.1 W/mK	
Electrical Properties:	
Dielectric Constant (1KHz): 5.40	Volume Resistivity @ 23°C: ≥ 2 x 10 ¹³ Ohm-cm
Dissipation Factor (1KHz): 0.004	

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